

## **A M E N D M E N T**

### **In the Specification:**

Please amend the specification as follows:

On page 2, please replace the paragraph that begins at line 27 with:

The presence of organics and other contaminants on a copper seed layer may interfere with wetting of the copper seed layer by an electrolyte during ECD. For example, the rate of copper deposition during ECD at contaminated areas may be low (or ~~be~~ nonexistent), resulting in voids in those areas. It would therefore be desirable to provide a metallization process which reduces or eliminates sources of voids, in order to increase device yield.